



INFORMATION DISCLOSURE  
CITATION

ATTY. DOCKET NO.

SERIAL NO.

4209-29

10/815,992

APPLICANT

EAST

FILING DATE

GROUP

April 2, 2004

3753

## U.S. PATENT DOCUMENTS

| EXAMINER<br>INITIAL | DOCUMENT NUMBER | DATE    | NAME                 | CLASS | SUBCLASS | FILING DATE<br>IF APPROPRIATE |
|---------------------|-----------------|---------|----------------------|-------|----------|-------------------------------|
| TD                  | 2002/0108743    | 8-2002  | Wirtz                |       |          |                               |
| TD                  | 4,880,052       | 11-1989 | Meyer, IV et al.     |       |          |                               |
| TD                  | 4,577,398       | 3-1986  | Sliwa et al.         |       |          |                               |
| TD                  | 5,688,716       | 11-1997 | DiStefano et al.     |       |          |                               |
| TD                  | 5,583,317       | 12-1996 | Mennucci et al.      |       |          |                               |
| TD                  | 5,777,259       | 7-1998  | Mennucci et al.      |       |          |                               |
| TD                  | 5,987,893       | 11-1999 | Schulz-Harder et al. |       |          |                               |
| TD                  | 6,014,312       | 1-2000  | Schulz-Harder et al. |       |          |                               |
| TD                  | 6,317,326       | 11-2001 | Vogel et al.         |       |          |                               |
| TD                  | 4,717,433       | 1-1988  | Weisert et al.       |       |          |                               |
| TD                  | 5,325,913       | 7-1994  | Altoz                |       |          |                               |
| TD                  | 5,526,867       | 6-1996  | Keck et al.          |       |          |                               |
|                     |                 |         |                      |       |          |                               |
|                     |                 |         |                      |       |          |                               |

## FOREIGN PATENT DOCUMENTS

| DOCUMENT | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION<br>YES NO |
|----------|------|---------|-------|----------|-----------------------|
|          |      |         |       |          |                       |
|          |      |         |       |          |                       |
|          |      |         |       |          |                       |

## OTHER DOCUMENTS (including Author, Title, Date, Pertinent pages, etc.)

|    |  |
|----|--|
| TD | Zheng et al, "Cylindrical Pin-Fin Fan-Sink Heat Transfer and Pressure Drop Correlations", IEEE Trans. Components and Packaging Technology, vol. 25, also ASME/JSME Thermal Engineering Joint Conference Proceedings, paper AJTE99-6197, 1999,  |
| TD | Wirtz, "High Performance Woven Mesh Heat Exchange", F49620-99-1-0286, 1999   |
| TD | "High Performance Woven Mesh Heat Exchange", Research Summary, AFOSR Contractors' Meeting in Turbulence and Rotation Flows, Albuquerque, NM, August 18-19, 1999  |
| TD | Xu et al, "In-Plane Effective Thermal Conductivity of Plain Weave Screen Laminates with Arbitrary Weave Parameters", Paper TED-AJ03-417, 6 <sup>th</sup> ASME/JSME Thermal Engineering Joint Conference, Hawaii, March 16-20, 2003   |
| TD | Xu et al, "In-Plane Effective Thermal Conductivity of Plain-Weave Screen Laminates", IEEE Trans. on Components and Packaging Tech., vol. 25, #4, 2003. See also Proc. THERMES 2002, pp. 231-242, Millpress, Rotterdam, January 2002  |
| TD | Wirtz et al, "Thermal/Fluid Characteristics of 3-D Woven Mesh Structures as Heat Exchanger Surfaces", IEEE Trans Components and Packaging Technology, vol. 26, 2003, pp.40-47. See also paper 1372, Eighth Intersociety Conference on Thermal Phenomena in Electronic Systems, San Diego, CA |
| TD | Li et al, "Development of a High-Performance Heat Sink Based on Screen-Fin Technology", Proc 19-th Semiconductor Thermal Measurement and Management Symposium, IEEE 02CH37437, March 6-10, 2003, pp. 53-60   |

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|-----------|--------------|-----------------|--------|
| *Examiner | <i>zhong</i> | Date Considered | 8/1/05 |
|-----------|--------------|-----------------|--------|

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application.

Form PTO-FB-A820 (Also PTO-1449)